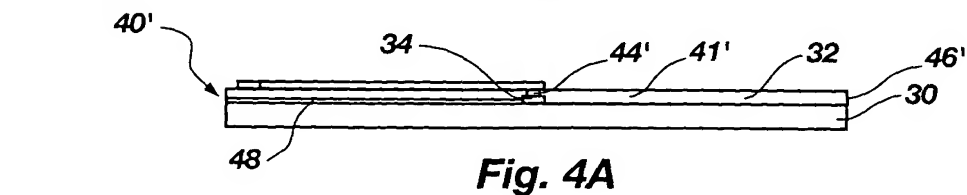
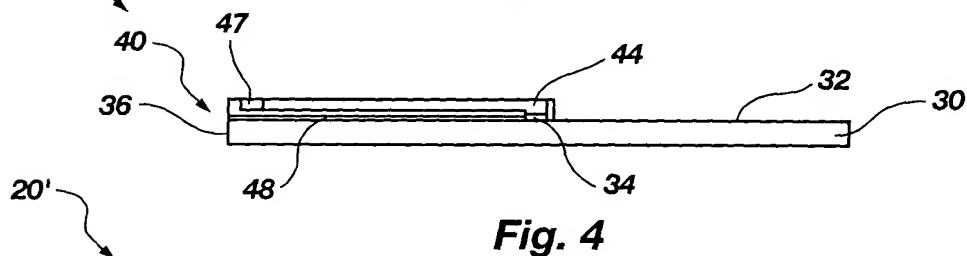
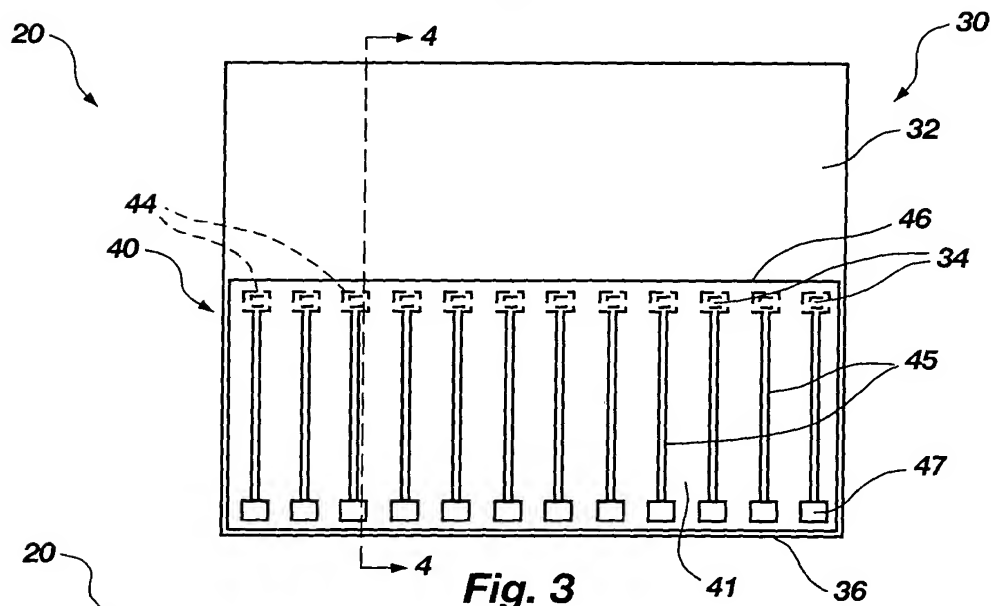
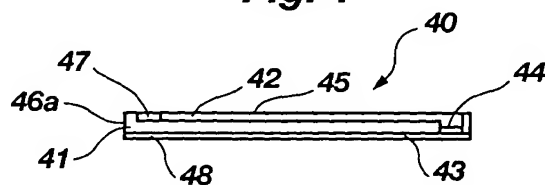
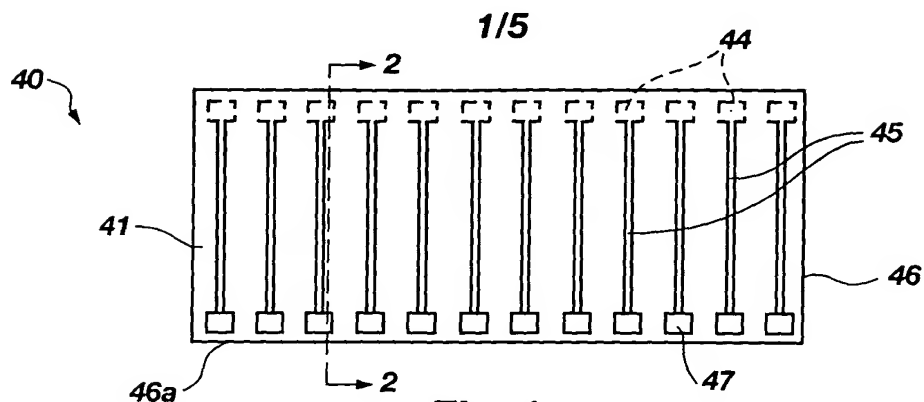


TITLE: METHODS FOR DESIGNING BOND PAD REROUTING
ELEMENTS FOR USE IN STACKED SEMICONDUCTOR DEVICE
ASSEMBLIES AND FOR ASSEMBLING SEMICONDUCTOR DEVICES

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Docket No.: 2269-4814.1US



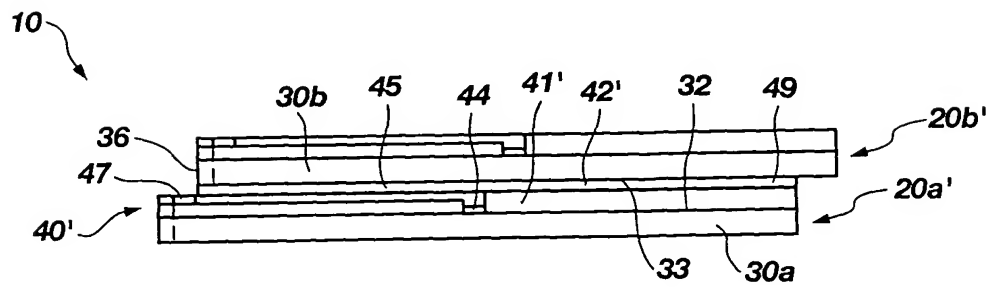


Fig. 5

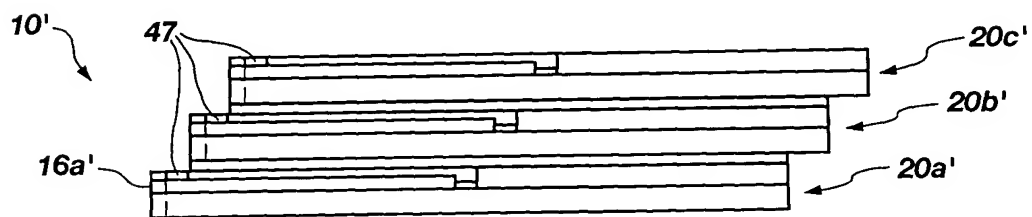


Fig. 6

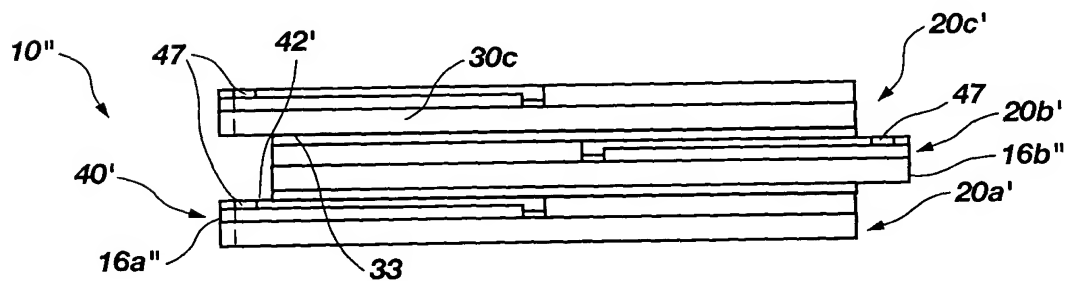


Fig. 7

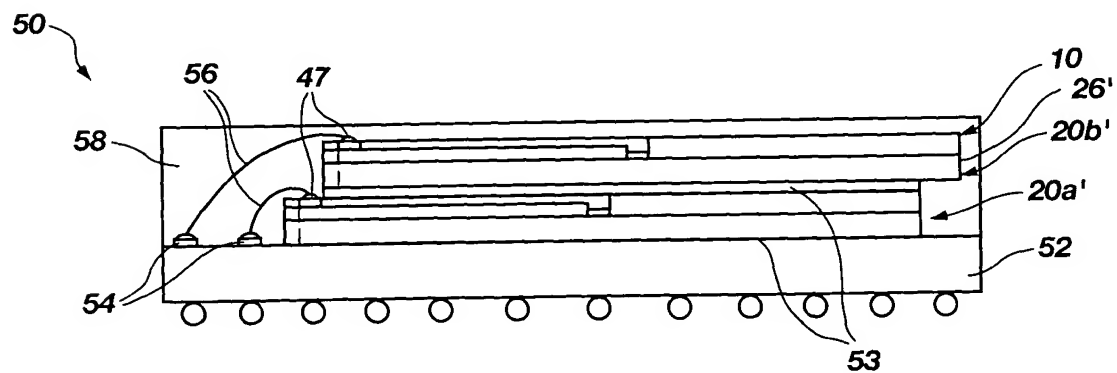


Fig. 8

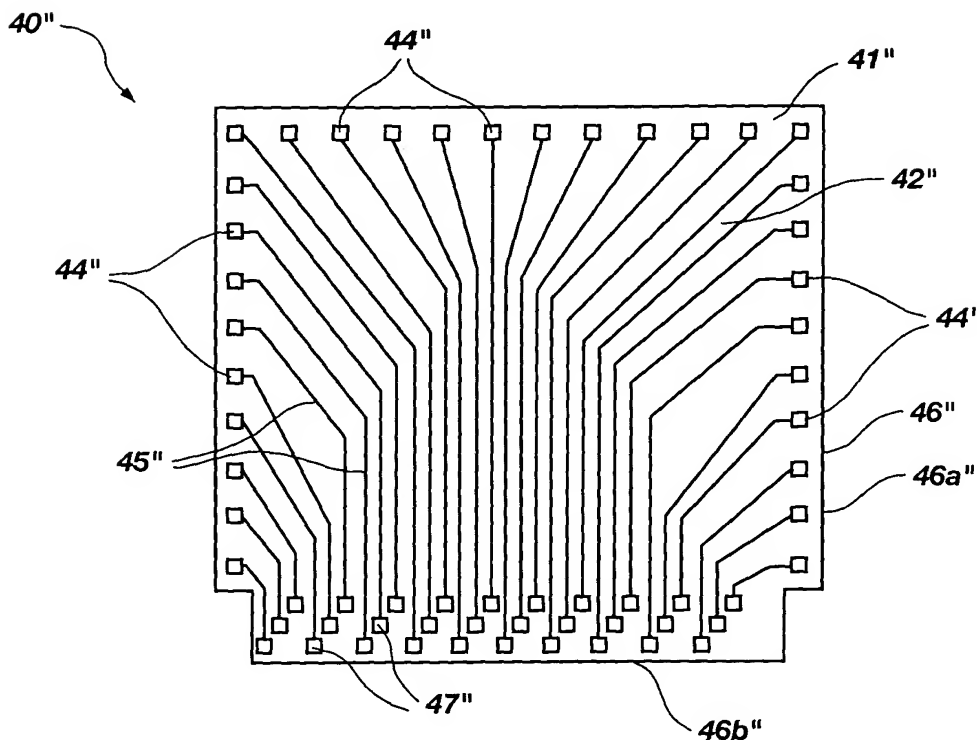


Fig. 9

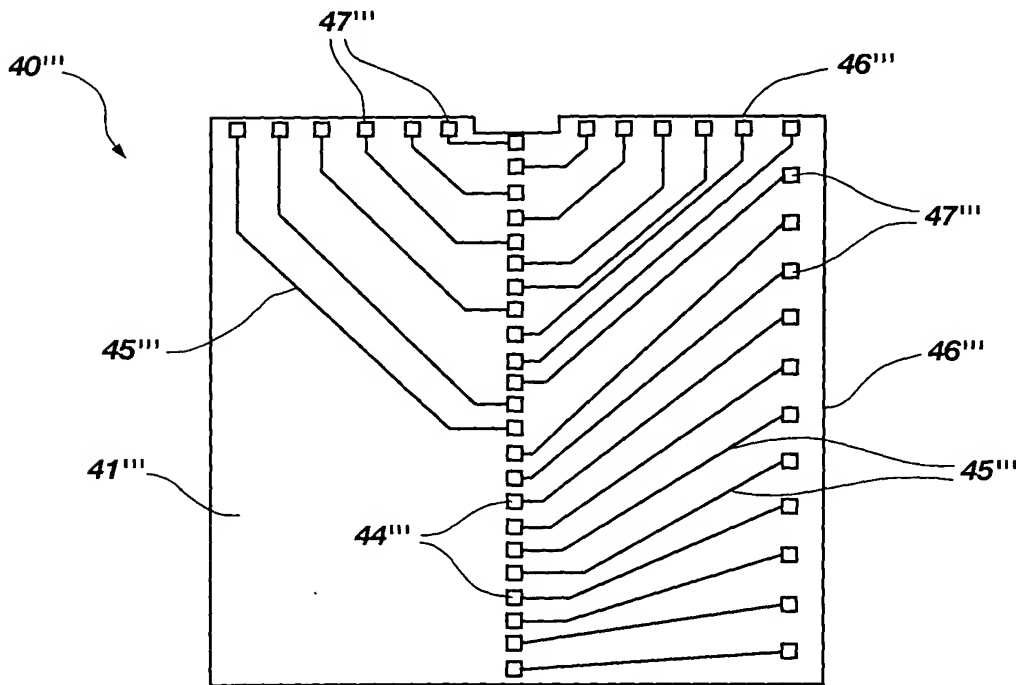


Fig. 10

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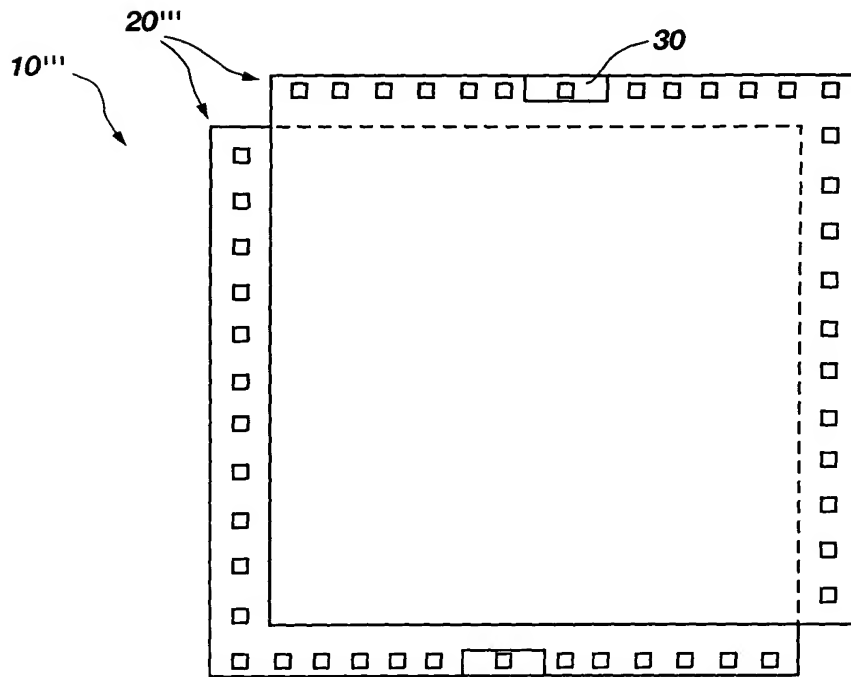


Fig. 11

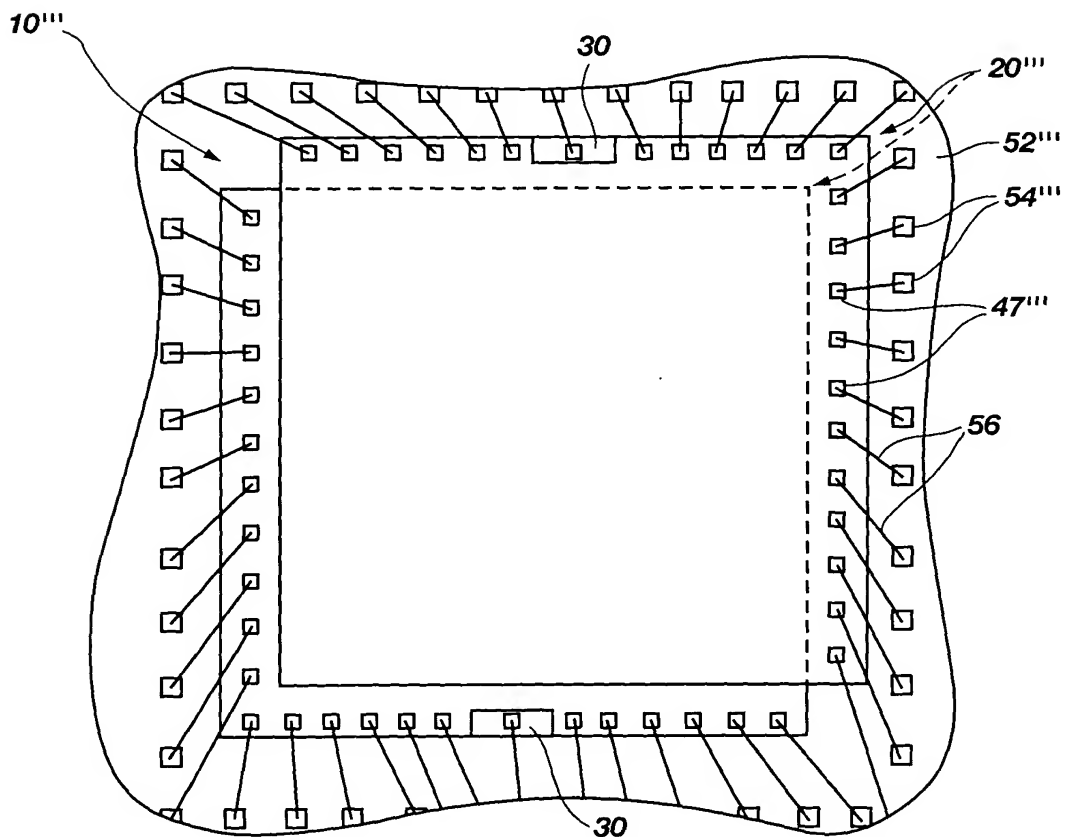


Fig. 12

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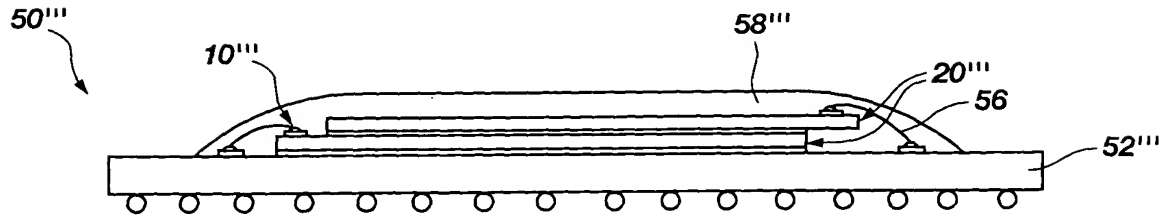


Fig. 13